

# US3AB~US3MB

Rev.A Dec.-2017



DATA SHEET

## / Descriptions

50V~1000V 3.0A SMB

Surface Mount Ultrafast Recovery Rectifier, Reverse Voltage:50 to1000V, Forward Current:3.0A, SMB package.

## / Features

RoHS 2011/65/EU

Glass Passivated Chip Junction High efficiency Lead free in comply with EU ROHS 2011/65/EU directives For surface mounted applications. Halogen free product.

## / Applications

General purpose.

## / Equivalent Circuit



## / Pinning



PIN	DESCRIPTION
1	Cathode
2	Anode



## / Marking

See Marking Instructions.

Note:

(1) P.C.B. mounted with 2.0 X 2.0" (5 X 5 cm) copper pad areass .

Parameter	Symbol	Test condition	Ra19.u7ng						Unit
			US3AB	US3BB	US3DB	US3GB	US3JB	US3KB	
Maximum Instantaneous Forward Voltage	$V_F$	$I_F=3.0A$	1.0			1.3	1.68		V
Maximum DC Reverse Current at Maximum DC Blocking Voltage	$I_R$	$T_a=25$	5.0						uA
		$T_a=125$	100						
Maximum Reverse Recovery Time	$T_{rr}$	$I_F=0.5A$							

/ Electrical Characteristic Curve

Fig.1 Maximum Average Forward Current Rating

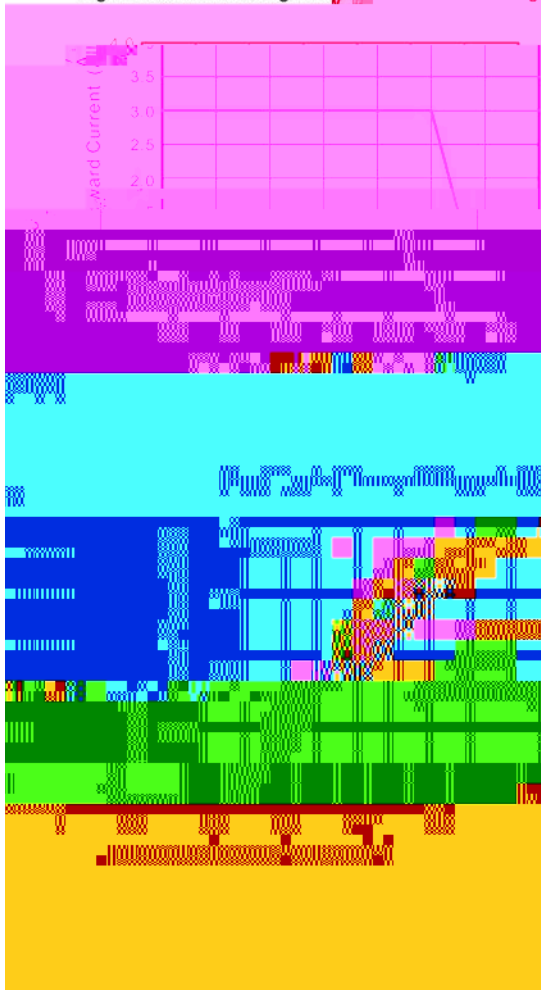
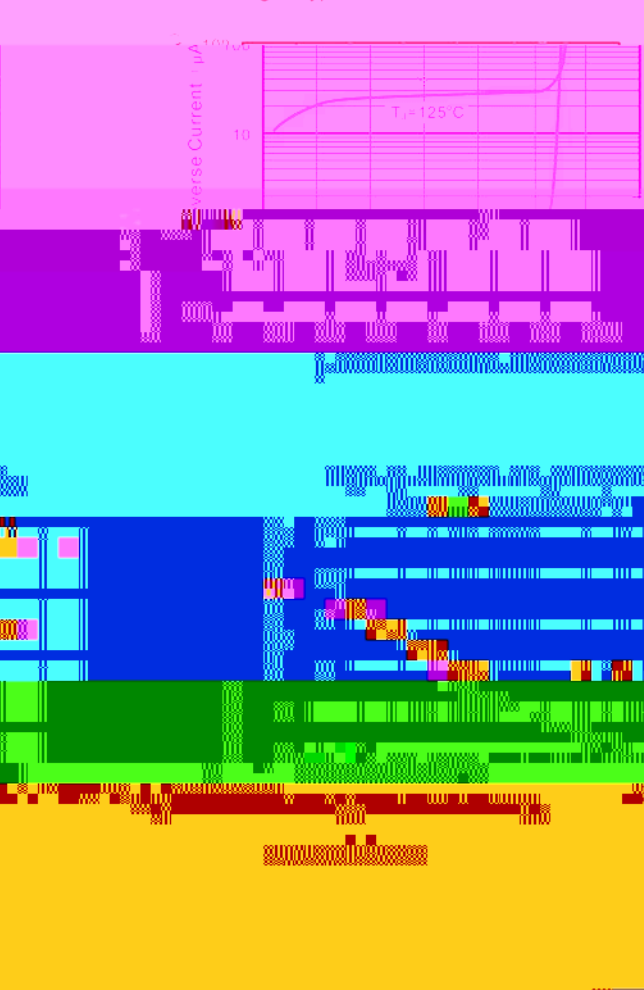


Fig.2 Typical Reverse Characteristics

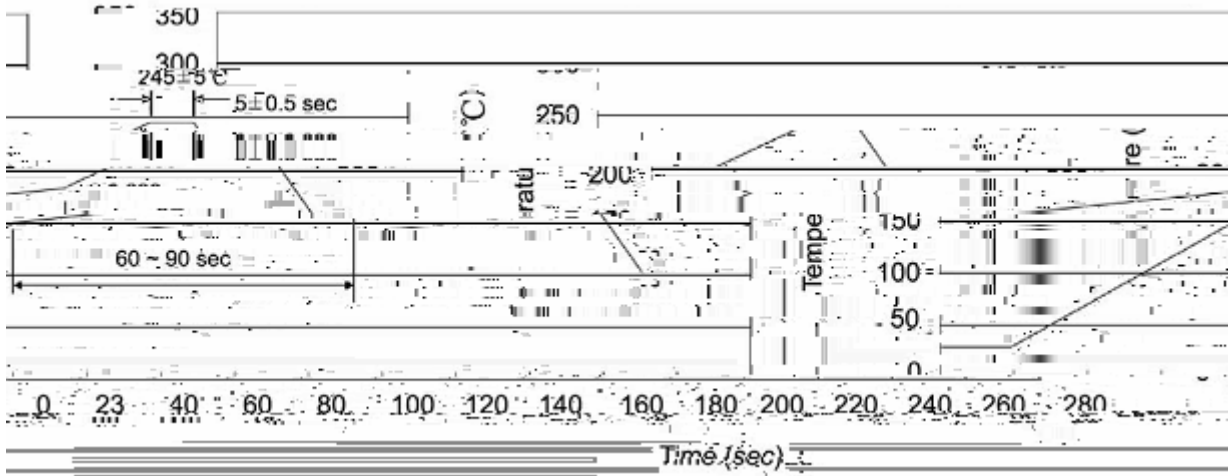


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( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- |   |       |     |       |          |   |
|---|-------|-----|-------|----------|---|
| 1 | 25    | 150 | 60    | 90sec;   | 1.Preheating:25~150 , Time:60~90sec.    |
| 2 | 245±5 |     | 5±0.5 | sec;     | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 |       |     | 2     | 10 /sec. | 3. Cooling Speed: 2~10 /sec.            |

/ Resistance to Soldering Heat Test Conditions

260±5 ±